

## Mask Set Errata for Mask REVA

### Introduction

This report applies to mask REVA for these products:

- MPC5534

ID before 15 MAY 2008	ID from 15 May 2008 to 30 JUNE 2010	ID after 1 JULY 2010	Errata Title
N/A	12488	2279	BAM: Pull RXD_A high during CAN serial boot mode
2297	7062	1722	BAM: Serial download unavailable to last 16 bytes (4 words) of System RAM
6049	5028	224	BAM: VLE added to the LENGTH field during serial boot message
2237	7461	2114	DMA: Dynamic writes to DMA control register can induce preemption failure
1123	6934	575	DSPI: Changing CTARs between frames in continuous PCS mode causes error
4031	5922	621	DSPI: DSPI D PCS[3:4] are slow speed pins
4022	11100	1154	DSPI: DSPI_B pins split to separate supply, VDDEH10
N/A	10483	1103	DSPI: PCS Continuous Selection Format limitation
2264	11097	1147	DSPI: Using DSPI in DSI mode with MTO may cause data corruption
N/A	9739	1082	DSPI: set up enough ASC time when MTFE=1 and CPHA=1
2379	7097	1756	EBI: Calibration pads are 1 ns slower than EBI
2823	7049	1708	EBI: Do not access external resources when the EBI is disabled
3111	11099	1151	EBI: Dual controller mode cannot be guaranteed under all conditions
3839	5762	1844	EBI: Timed out accesses (external TA only) may generate spurious TS_B pulse
3819	5715	1741	EQADC : 25% calibration channel sampling requires at least 64 sampling cycles
1742	6968	652	EQADC: 50% reference channels reads 20 mv low
2371	7439	2075	FLASH: Large blocks limited to 1,000 Program/erase cycles

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ID before 15 MAY 2008	ID from 15 May 2008 to 30 JUNE 2010	ID after 1 JULY 2010	Errata Title
2419	6946	605	FLASH: Minimum Programming Frequency is 25 MHz
2742	7124	1784	FLASH: PRD must be set before setting the flash wait states to 0
4726	5757	1835	FLASH: Program or Erase operation could fail at -40C if VDD is less than 1.40 volts
1745	7444	2083	FLASH: The ADR register may get loaded with a flash address even through no ECC error has occurred
715	6764	1111	FMPLL: LOLF can be set on MFD change
N/A	8014	2181	FMPLL: Non-zero pre-divider values can cause PLL lock failure
N/A	18087	1232	FMPLL: Reset may not be negated if an external reset occurs during a software initiated PLL relock sequence
		6531	FMPLL: Selecting GPIO mode on RSTCFG/PLLCFG[0:1] may cause PLL failure after a reset
		3407	FlexCAN: CAN Transmitter Stall in case of no Remote Frame in response to Tx packet with RTR=1
4414	5952	1557	FlexCAN: Corrupt ID may be sent in early-SOF condition
N/A	23304	2685	FlexCAN: Module Disable Mode functionality not described correctly
3567	5804	352	FlexCAN: New feature - Individual RX matching and Message Queuing
3566	6413	1654	FlexCAN: New feature - Self reception disable
3138	5790	1895	FlexCAN: New feature - Transmit (TX)/Receive (RX) Warning Interrupts
N/A	34749	2424	FlexCAN: switching CAN protocol interface (CPI) to system clock has very small chance of causing the CPI to enter an indeterminate state
1698	6900	1620	MPC5533: PARTNUM is incorrect
2616	6978	677	MPC5533: SIU_MIDR Revision field is 0x0010, DID[PIN]=0x134
3487	5730	1795	MPC5534: Flash settings documentation is incorrect
2486	6907	1650	MPC5534: SIU_MIDR Revision field is 0x0010, DID[PIN]=0x134
N/A	40092	6726	NPC: MCKO clock may be gated one clock period early when MCKO frequency is programmed as SYS_CLK/8.and gating is enabled
1800	7216	1957	NPC: MCKO_DIV can be set to 0x0 (1X MCKO)
2806	7057	1717	NZ3C3: Data Trace of stmw instructions may cause overruns
2054	6943	597	NZ3C3: Nexus I-CNT same for Indirect Branches and Exceptions
2538	7065	1727	NZ3C3: No sync message generated after 255 direct branch messages in history mode
4706	5785	1886	Pad Ring: ESD Specifications are not met
4381	5934	1528	Pad Ring: Pin behavior during power sequencing
63	6700	488	Pad Ring: Possible poor system clock just after POR negation.
64	7224	1969	Pad Ring: RSTOUT is 3-stated during the power-on sequence.
		3377	Pad Ring:Nexus pins may drive an unknown value immediately after power up but before the 1st clock edge
3685	5724	1779	SIU: CRSE bit added to the SIU Configuration Register
N/A	9319	1053	XBAR: Illegal values can be written into the Master Priority Field
3415	5743	1813	e200z3: Debug interrupt (IVOR15) can be taken erroneously

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ID before 15 MAY 2008	ID from 15 May 2008 to 30 JUNE 2010	ID after 1 JULY 2010	Errata Title
2501	6916	1682	e200z3: JTAG Part Identification is 0x6
5093	11091	1136	eDMA: BWC setting may be ignored between 1st and 2nd transfers and after the last write of each minor loop.
2305	7147	1834	eMIOS: OPMWC unable to produce close to 100% duty cycle signal
2651	7110	1769	eMIOS: Updating the B register requires 32-bit writes.
2878	7114	1773	eQADC: conversions of muxed digital/analog channels close to the rail
N/A	8632	1013	eSCI : Automatic reset of the LIN state machine cause incorrect transmission
N/A	27326	1381	eSCI: LIN Wakeup flag set after aborted LIN frame transmission
N/A	17048	1221	eSCI: LIN bit error indicated at start of transmission after LIN reset
N/A	8635	1017	eSCI: LIN fast bit error detection causes incorrect LIN reception
N/A	8173	2190	eSCI: LIN slave timeout flag STO not asserted if CRC is received too late
7064	4968	1614	eSCI: Low pulse on LIN RX line may prevent assertion of transmit data ready flag ESCI_SR[TXRDY]
2477	6965	644	eTPU: MISSCNT can fail on sequential physical teeth
7331	3377	112	eTPU: Prescaler phase shift between TCR1 and TCR2
3150	5710	1728	eTPU: STAC bus export may skip 1 count

### **e2279: BAM: Pull RXD\_A high during CAN serial boot mode**

**Errata type:** Errata

**Description:** The Boot Assist Module (BAM) disables the internal pull up resistor on serial port A receive data pin (eSCI RXD\_A) during serial boot mode operation. If the pin is not actively driven by system, its input level may drift below low threshold and be recognized as a valid eSCI boot operation thus preventing CAN boot mode selection.

**Workaround:** Always drive the eSCI RXD\_A pin high during CAN serial boot mode. A external 10K pullup resistor can be used for this purpose.

### **e1722: BAM: Serial download unavailable to last 16 bytes (4 words) of System RAM**

**Errata type:** Information

**Description:** When using the BAM Serial boot download feature, the BAM initializes an additional 4 32-bit words after the end of the downloaded records. This is done to insure that if the core fetches the last instruction of the downloaded code from the internal SRAM while executing the code, it will not prefetch instructions from memory locations that have not been initialized.

Note: if the download image has the exact same size as the internal SRAM, the 20 bytes at the beginning of the SRAM will be written with zero value due to incomplete memory decoding.

**Workaround:** When using the Serial download feature of the BAM, make sure that the maximum address of the downloaded code does not exceed the end address of the SRAM minus 16 bytes or the last address of the Memory Management Unit (MMU) entry minus 16 bytes (for devices with MMU and the SRAM MMU setting less than the full SRAM size), whichever is smaller.

## **e224: BAM: VLE added to the LENGTH field during serial boot message**

**Errata type:** Information

**Description:** In serial boot mode, tools download 3 pieces of information: a 64-bit password, followed by a 32-bit start address, and then a 32-bit download length (LENGTH). On devices that support the Variable Length Encoded (VLE) instruction set, the 32-bit LENGTH field has been changed to a 1-bit VLE bit followed by a 31-bit LENGTH. The VLE bit replaces what was the MSB of the LENGTH. Setting the VLE bit to 1 indicates that the downloaded code should be run in VLE mode. Leaving VLE a 0 indicates that the downloaded code should be run in BookE/classic Power Architecture instruction set mode. When the VLE bit is set to 1 the BAM programs EBI, RAM and Flash MMU TLB entries (# 1,2 and 3) with the VLE attribute.

**Workaround:** Set the VLE bit (MSB of the 32-bit LENGTH) in the serial boot download data if the code being downloaded uses (was written in) VLE instructions.

## **e2114: DMA: Dynamic writes to DMA control register can induce preemption failure**

**Errata type:** Errata

**Description:** If the DMA control register (EDMA\_CR) is written while a channel is in the process of being preempted by a higher priority channel, the preemption process may be treated as spurious. In this case, the original channel is not preempted but its priority and preemption enable bit are temporarily replaced with those of the channel that caused the spurious preemption. After the lower priority channel completes its transfer, its original priority is restored and the higher priority channel starts its transfer.

This temporary priority change may cause further blocking of higher priority preempting channels.

**Workaround:** Do not use the channel preemption feature or if you use preemption, don't write the DMA control register when a preemptable channel is executing.

## **e575: DSPI: Changing CTARs between frames in continuous PCS mode causes error**

**Errata type:** Errata

**Description:** Erroneous data could be transmitted if multiple Clock and Transfer Attribute Registers (CTAR) are used while using the Continuous Peripheral Chip Select mode (DSPIx\_PUSHR[CONT=1]). The conditions that can generate an error are:

- 1) If DSPIx\_CTARn[CPHA]=1 and DSPIx\_MCR[CONT\_SCKE = 0] and DSPIx\_CTARn[CPOL, CPHA, PCSSCK or PBR] change between frames.
- 2) If DSPIx\_CTARn[CPHA]=0 or DSPIx\_MCR[CONT\_SCKE = 1] and any bit field of DSPIx\_CTARn changes between frames except DSPIx\_CTARn[PBR].

**Workaround:** When generating DSPI bit frames in continuous PCS mode, adhere to the aforementioned conditions when changing DSPIx\_CTARn bit fields between frames.

## e621: DSPI: DSPI D PCS[3:4] are slow speed pins

**Errata type:** Information

**Description:** The eMIOS[10:11]/PCSD[3:4]/GPIO[189:190] pins have a pad type of SH (slow speed pad) instead of MH (medium speed pad). While the eMIOS function normally does not require a medium speed pad, when the pin is configured as the Deserial Serial Peripheral Interface D Peripheral Chip Select (DSPI\_PCSxD), the slow pad may limit the maximum speed of the DSPI port.

**Workaround:** Either don't use the DSPI\_D PCS functions on these pins or limit the frequency of the DSPI port to account for the difference in slew rate of the pins. The slow pads have a slew rate of 15 to 200 ns and the medium speed pads have a slew rate of 8 to 100 ns (both with a 50 pF load) depending on the setting of the Slew Rate Control bits in the Pad Configuration register (PCRx[SR]).

## e1154: DSPI: DSPI\_B pins split to separate supply, VDDEH10

**Errata type:** Information

**Description:** The DSPI\_B SINB, SOUTB, SCKB, PCS\_B[0:2] were separated from the VDDEH6 and are now powered by the new power supply pin VDDEH10. Ball J23 on the 416 package was changed from being a duplicate VDDEH6 pin to being a separate VDDEH10 supply pin. 324 pin package drawings show the VDDE10 ball placement. VDDEH6 and VDDEH10 are combined/shorted internally on 208 packages.

**Workaround:** For compatibility to the MPC5554, always power VDDEH6 and VDDEH10 from the same power supply (3.0 to 5.25 volts). If compatibility is not required to the MPC5554, VDDEH10 and VDDEH6 can be supplied by different voltage supplies. This allows one DSPI to operate at a different voltage than the other DSPI modules (3.3 and 5 volts, for example).

## e1103: DSPI: PCS Continuous Selection Format limitation

**Errata type:** Errata

**Description:** When the DSPI module has more than one entry in the TX FIFO and only one entry is written and that entry has the CONT bit set, and continuous SCK clock selected the PCS levels may change between transfer complete and write of the next data to the DSPI\_PUSHR register.

For example:

If the CONT bit is set with the first PUSHR write, the PCS de-asserts after the transfer because the configuration data for the next frame has already been fetched from the next (empty) fifo entry. This behavior continues till the buffer is filled once and all CONT bits are one.

**Workaround:** To insure PCS stability during data transmission in Continuous Selection Format and Continuous SCK clock enabled make sure that the data with reset CONT bit is written to DSPI\_PUSHR register before previous data sub-frame (with CONT bit set) transfer is over.

## e1147: DSPI: Using DSPI in DSI mode with MTO may cause data corruption

**Errata type:** Errata

**Description:** Using the DSPI in Deserial Serial Interface (DSI) Configuration (DSPIx\_MCR[DCONF]=0b01) with multiple transfer operation (DSPIx\_DSICR[MTOE=1]) enabled, may cause corruption of data transmitted out on the DSPI master if the clock Phase is set for leading edge capture DSPIx\_CTARn[CPHA]=0. The first bit shifted out of the master DSPI into the slave DSPI module will be corrupted and will convert a '0' to read as a '1'.

**Workaround:** There are three possible workarounds for this issue.

- 1) Select CPHA=1 if suitable for external slave devices.
- 2) Set first bit to '1', or ignore first bit. This may not be a workable solution if this bit is required.
- 3) Connect SOUT from the master to SIN of the first slave externally instead of using internal signals. This is achieved by setting the DSPI Input Select Register (SIU\_DISR) to set the SINSELx field of the first slave DSPI to '00' and configuring this slave's SIN pin and master SOUT pin as DSPI SIN/SOUT functions respectively. This workaround is suitable only if these two signals are available to be connected externally to each other.

### **e1082: DSPI: set up enough ASC time when MTFE=1 and CPHA=1**

**Errata type:** Information

**Description:** When the DSPI is being used in the Modified Transfer Format mode (DSPI\_MCR[MTFE]=1) with the clock phase set for Data changing on the leading edge of the clock and captured on the following edge in the DSPI Clock and Transfer Attributes Register (DSPI\_CTARn[CPHA]=1), if the After SCK delay scaler (ASC) time is set to less than 1/2 SCK clock period the DSPI may not complete the transaction - the TCF flag will not be set, serial data will not received, and last transmitted bit can be truncated.

**Workaround:** If the Modified Transfer Format mode is required DSPI\_MCR[MTFE]=1 with the clock phase set for serial data changing on the leading edge of the clock and captured on the following edge in the SCK clock (Transfer Attributes Register (DSPI\_CTARn[CPHA]=1) make sure that the ASC time is set to be longer than half SCK clock period.

### **e1756: EBI: Calibration pads are 1 ns slower than EBI**

**Errata type:** Information

**Description:** The calibration bus outputs and input setup time is 1ns longer than the equivalent normal External bus signals. Therefore, the electrical specifications need to be added to the data sheets for the calibration signals.

**Workaround:** For synchronous (to CLKOUT) peripherals on the calibration pads, make certain that the bus will meet the new electrical specification.

### **e1708: EBI: Do not access external resources when the EBI is disabled**

**Errata type:** Information

**Description:** When the external bus is disabled in the External Bus Interface Module Control Register (EBI\_MCR[MDIS] = 1), accesses through the EBI will not terminate and the master requesting the access will not request another one.

**Workaround:** Do not disable the EBI or do not allow accesses to the external bus through Memory Management Unit (MMU) settings in the core. Other internal bus masters (such as DMA) bypasses the MMU and therefore these accesses will hang the external bus if the destination is in the external bus address map.

## e1151: EBI: Dual controller mode cannot be guaranteed under all conditions

**Errata type:** Errata

**Description:** In dual controller mode, the specification for the phase relationship between EXTAL and CLKOUT is +/- 1 ns, however this does not allow adequate set up and hold times to guarantee successful operation of the external bus to a second MCU.

**Workaround:** Do not use in Dual Controller mode.

## e1844: EBI: Timed out accesses (external TA only) may generate spurious TS\_B pulse

**Errata type:** Errata

**Description:** When an external Transfer Acknowledge (TA) access times out, there is a boundary case where the External Bus Interface (EBI) asserts a Transfer Start (TS) pulse as if starting another access, even if no other internal request is pending. The boundary case is when the access is part of a "small access" set (sequence of external accesses to satisfy 1 internal request), and when the external TA arrives around the same cycle (+/- 1 clkout cycle) as the bus monitor timeout (BMT).

Most EBI signals will stay negated during this erroneous transfer (CS, OE, WE, BDIP). However, along with TS assertion, RD\_WR may also assert (for 1 cycle only, during this phantom TS), if the prior access that timed out was a write. This condition can generate an erroneous write transfer (with CS negated). The address (ADDR pins) will be incremented to the address of the next small access transfer that would have been performed, and the value driven by the EBI on the DATA bus (if a write) may change. Busy Busy (BB) may be asserted along with the phantom TS (if external master modes is enabled in the EBI Module configuration Register, SIU\_MCR[EXTM]=1), and the Transfer Size (TSIZ) value may change.

Internally, the EBI terminates the timeout access, and the internal state machine goes to IDLE after the timeout access. So the EBI will not be "hung" after the spurious TS, and the EBI does respond properly to future internal or external requests.

However, the side effect of the spurious TS is that it may cause an external non-chip-select device to think an access is being performed to it, resulting in 1 of 2 bad effects (depending on RD\_WR value during spurious TS):

- 1) RD\_WR high (read): ext. device may drive back read data some number of cycles later, possibly conflicting with a future real access (e.g. write) that might have started by that time.
- 2) RD\_WR low (write): ext. device may get an erroneous write performed to it

Note that the soonest possible TS for a real transfer (after the timeout transfer), is 2 cycles after the spurious TS (so 1 cycle gap), meaning this Bug will never result in a 2-cycle TS pulse.

**Workaround:** Do not enable bus monitor in the EBI Bus Monitor Control Register (keep SIU\_BMCR[BME]=0), unless at least 1 of the following 3 conditions can be met:

- 1) The external TA will never be asserted from external device within 1 cycle of when the access would be timing out (see NOTE below)

2) No internal requests greater than external bus size will be performed (e.g. doing data-only fetches of 32 bits or less on 32-bit data bus or 16 bits or less on a 16 bit bus only, so a "small access" could never occur).

3) The side effect of this TS pulse driven to non-CS device is judged to be tolerable in system after a timeout error occurs; depends on spec of external device and user requirements for data coherency after a timeout error occurs.

NOTE: Of the 3 above, #1 is easiest to achieve in most systems. If the maximum possible TA latency of the external device is known, the user just needs to set the BMT period more than (external device maximum latency + 2), and this condition will not occur.

### **e1741: EQADC : 25% calibration channel sampling requires at least 64 sampling cycles**

**Errata type:** Information

**Description:** The 25%\*(VRH-VRL) calibration channel (ADC channel 44) will not convert to specification with an ADC sample time less than 64 cycles.

**Workaround:** For accurate calibration, the 25% calibration channel should be converted using the Long Sample Time (LST) setting for either 64 or 128 ADC sample cycles in the ADC Conversion Command Message (LST = 0b10 or 0b11).

### **e652: EQADC: 50% reference channels reads 20 mv low**

**Errata type:** Information

**Description:** The equation given for the definition of the 50% reference channel (channel 42) of the Enhanced Queued Analog to Digital Converter (eQADC) is not correct. The 50% reference point will actually return approximately 20mV (after calibration) lower than the expected 50% of difference between the High Reference Voltage (VRH) and the Low Reference Voltage (VRL).

**Workaround:** Do not use the 50% point to calibrate the ADC. Only use the 25% and 75% points for calibration.

After calibration, software should expect that the 50% Reference will read 20 mV low.

### **e2075: FLASH: Large blocks limited to 1,000 Program/erase cycles**

**Errata type:** Errata

**Description:** The electrical specification for Program/Erase cycling on large Flash blocks (all 128K blocks - Middle Address Space [MAS] blocks M0 and M1, plus High Address Space [HAS] blocks H0 to H3/H7/H11/H19 [depending on total flash size]) has been changed to 1,000 PE cycles minimum. The small blocks (16K, 48K, and 64K - Low Address Space [LAS] blocks L0-L5) are still specified as 100,000 PE cycles minimum.

The data retention specification all blocks is still 20 years for blocks cycled less than 1000 times and 5 years for blocks cycled 1001 to 100,000 cycles (1,000 for large blocks).

**Workaround:** Only use the small blocks for EEPROM emulation (LAS L0-L5). Do not use blocks MAS M0/M1 or HAS H0 to H3/H7/H11/H19 (depending on total flash size) for EEPROM emulation requiring greater than 1,000 Program/Erase cycles. Refer to the latest device electrical specifications (Data Sheet) dated July 2007 or later.

### **e605: FLASH: Minimum Programming Frequency is 25 MHz**

**Errata type:** Information

**Description:** Programming and erase operations of the internal flash could fail if the clock to the flash (usually the system clock) is less than 25 MHz.

**Workaround:** Do not program or erase the flash when the system operating frequency is below 25MHz.

### **e1784: FLASH: PRD must be set before setting the flash wait states to 0**

**Errata type:** Information

**Description:** The Pipeline Read Disable (PRD), bit 24 in the Flash Module Control Register (FLASH\_MCR, address 0xC3FC\_8000), is not documented. PRD should be set at low system frequencies that allow a one clock cycle flash read access.

**Workaround:** Set PRD (FLASH\_MCR[PRD]=1] before the Read Wait State Control (RWSC) is set to 0 in the Flash Bus Interface Unit Control Register (FLASH\_BIUCR, address 0xC3F8\_801C).

### **e1835: FLASH: Program or Erase operation could fail at -40C if VDD is less than 1.40 volts**

**Errata type:** Errata

**Description:** A flash program or erase function may fail, indicated by a cleared Program/Erase Good bit in the Flash Module Configuration Register following a program or erase operation (FLASH\_MCR[PEG]=0b0), if the VDD operating voltage is below 1.40 volts (either using an external 1.5 volt regulator or the internal regulator) at -40 degrees Celsius.

**Workaround:** Either: 1) Restrict erase and program operation to a minimum VDD greater than 1.40V, [this allows for full specified operating temperature] if using an external 1.5V supply. If the internal regulator controller is used and the proper Freescale recommendations for the VRC circuitry have been met (see data sheet), the internal regulator will hold the voltage above 1.40 volts and will not have a failure;

or

2) Restrict erase and program operation to a minimum ambient temperature of 25C [allows for full specified operating voltage] if using an external regulator that could drop as low as 1.35 volts.

### **e2083: FLASH: The ADR register may get loaded with a flash address even through no ECC error has occurred**

**Errata type:** Information

**Description:** The Flash Address Register (FLASH\_AR) may be loaded with a flash address when no Error Correction Code (ECC) has occurred. When an ECC does occur, the FLASH\_AR is properly set.

**Workaround:** Check the Flash Module Control Register ECC Event Error (FLASH\_MCR[EER]=1) to check for an ECC error before examining the ADR register. If an error has occurred then the ADR register data is valid. If an error has not occurred then the FLASH\_AR data could change on any flash access.

### e1111: FMPLL: LOLF can be set on MFD change

**Errata type:** Errata

**Description:** Normally, the Loss of Lock Flag (FMPLL\_SYNCR[LOLF]) would not be set if the loss of lock occurred due to changing of the Multiplication Factor Divider bits or PREDIV bits (FMPLL\_SYNCR[MFD] or [PREDIV]) or enabling of Frequency Modulation (FMPLL\_SYNCR[Depth]>0b00). However, if LOLF has been set previously (due to an unexpected loss of lock condition) and then cleared (by writing a 1), a change of the MFD, PREDIV or DEPTH fields can cause the LOLF to be set again which can trigger an interrupt request if LOLIRQ bit is set.

In addition, changing the RATE bit will also set the LOLF regardless of previous conditions.

**Workaround:** The Loss of Lock Interrupt Request enable in the Synthesizer Control Register (FMPLL\_SYNCR[LOLIRQ]) should be cleared before any change to the multiplication factor (MFD), PREDIV, modulation depth (DEPTH), or modulation rate (RATE) to avoid unintentional interrupt requests. After the PLL has locked (LOCK=1), LOLF should be cleared (by writing a 1) and LOLIRQ may be set again if required.

### e2181: FMPLL: Non-zero pre-divider values can cause PLL lock failure

**Errata type:** Errata

**Description:** When configuring the MPC55xx Frequency Modulated Phase Lock Loop (FMPLL) in crystal or external reference clock mode, the system clock frequency (SYSCLK) is determined by the values programmed into the Pre-Divider (PREDIV), Multiplication Factor Divider (MFD), and Reduced Frequency Divider (RFD) fields in the FMPLL Synthesizer Control Register (FMPLL\_SYNCR). If the pre-divider is set to divide by 2, 3, 4, or 5 (FMPLL\_SYNCR[PREDIV] = 1, 2, 3, or 4), a condition may occur in which the FMPLL will fail to lock. Odd predividers may result in the PLL stuck in a lock routine where it can not escape. Even predividers may result in the PLL VCO frequency not being able to reach target frequencies below 110MHz. To clear this condition when it occurs, the part must be powered down.

**Workaround:** If a pre-divider of 2, 3, 4, or 5 must be used in order to achieve the desired system clock frequency, any write that causes a relock of the FMPLL (changing either the PREDIV or MFD) with a FMPLL\_SYNCR[PREDIV] = 1, 2, 3, or 4 must occur with the current system frequency set to one-half of the crystal frequency or less through setting of the PLL RFD prior to writing the MFD or PREDIV.

NOTE: When programming the FMPLL, care must also be taken not to violate the maximum system clock frequency of the device, or the maximum and minimum frequency specifications of the FMPLL.

### e1232: FMPLL: Reset may not be negated if an external reset occurs during a software initiated PLL relock sequence

**Errata type:** Errata

**Description:** During a software initiated change in frequency of the Phase Lock Loop (PLL) to a frequency greater than 112 MHz, if reset is externally asserted, it is possible that reset will never be exited.

**Workaround:** Do not allow external resets to be applied during a software initiated PLL frequency change that requires a relock of the PLL. A possible way to prevent this from occurring is to use a GPIO signal to gate (hold off) the RESET input to the device from the external power supply. The following sequence would have to be used:

- 1) drive GPIO to hold RESET negated,
- 2) Start the PLL lock sequence,
- 3) wait for PLL lock sequence to complete,
- 4) Toggle the GPIO pin to allow the external reset to assert the RESET pin.

### **e6531: FMPLL: Selecting GPIO mode on RSTCFG/PLLCFG[0:1] may cause PLL failure after a reset**

**Errata type:** Errata

**Description:** If the General Purpose Input/Output (GPIO) mode is selected in software for the PLLCFG[0:1] and/or the RSTCFG pins AND the default clock reference mode (crystal reference) is not used, any RESET assertion of the device (internal or external) may corrupt the operating mode of the PLL and the microcontroller may not exit reset (RSTOUT will not negate).

**Workaround:** Do not enable the GPIO mode in software for the PLLCFG[0:1]/RSTCFG pins when over-riding the default (crystal) PLL clock mode (RSTCFG=0 AND PLLCFG[0:1] != 0b10).

### **e3407: FlexCAN: CAN Transmitter Stall in case of no Remote Frame in response to Tx packet with RTR=1**

**Errata type:** Errata

**Description:** FlexCAN does not transmit an expected message when the same node detects an incoming Remote Request message asking for any remote answer.

The issue happens when two specific conditions occur:

- 1) The Message Buffer (MB) configured for remote answer (with code "a") is the last MB. The last MB is specified by Maximum MB field in the Module Configuration Register (MCR[MAXMB] ).
- 2) The incoming Remote Request message does not match its ID against the last MB ID.

While an incoming Remote Request message is being received, the FlexCAN also scans the transmit (Tx) MBs to select the one with the higher priority for the next bus arbitration. It is expected that by the Intermission field it ends up with a selected candidate (winner). The coincidence of conditions (1) and (2) above creates an internal corner case that cancels the Tx winner and therefore no message will be selected for transmission in the next frame. This gives the appearance that the FlexCAN transmitter is stalled or "stops transmitting".

The problem can be detectable only if the message traffic ceases and the CAN bus enters into Idle state after the described sequence of events.

There is NO ISSUE if any of the conditions below holds:

- a) The incoming message matches the remote answer MB with code "a".

- b) The MB configured as remote answer with code "a" is not the last one.
- c) Any MB (despite of being Tx or Rx) is reconfigured (by writing its CS field) just after the Intermission field.
- d) A new incoming message sent by any external node starts just after the Intermission field.

**Workaround:** Do not configure the last MB as a Remote Answer (with code "a").

### e1557: FlexCAN: Corrupt ID may be sent in early-SOF condition

**Errata type:** Errata

**Description:** This erratum is not relevant in a typical CAN network, with oscillator tolerances inside the specified limits, because an early start of frame condition (early-SOF) should not occur.

An early-SOF may only be a problem if the oscillators in the network operate at opposite ends of the tolerance range (maximum 1.58%), which could lead to a cumulated phase error after 10 bit-times larger than phase segment 2.

A corrupt ID will be sent out if a transmit message buffer is identified for transmission during INTERMISSION, and an early-SOF condition is entered due to a dominant bit being sampled during bit 3 of INTERMISSION.

The message sent will be taken from the newly set up transmit buffer (Tx MB), with the exception of the 1st 8 ID bits, which are taken from the previously selected Tx MB.

The CRC is correctly calculated on the resulting bit stream so that receiving nodes will validate the message.

The early-SOF condition is detailed in the Bosch CAN Specification Version 2.0 Part B, Section 3.2.5 INTERFRAME SPACING - INTERMISSION.

**Workaround:** 1) Configure Tx MBs during FREEZE mode, or

2) Out of FREEZE mode, configure Tx MBs during bus idle:

- For networks with low traffic, determine Bus Idle status by reading the Idle bit of the Error and Status register (CANx\_ESR[IDLE]).

- For networks with high traffic, configure Tx MBs after the 3rd bit of intermission, and before the third bit of the CRC field from the next transmission.

### e2685: FlexCAN: Module Disable Mode functionality not described correctly

**Errata type:** Errata

**Description:** Module Disable Mode functionality is described as the FlexCAN block is directly responsible for shutting down the clocks for both CAN Protocol Interface (CPI) and Message Buffer Management (MBM) sub-modules. In fact, FlexCAN requests this action to an external logic.

**Workaround:** In FlexCAN documentation chapter:

Section "Modes of Operation", bullet "Module Disable Mode":

Where is written:

"This low power mode is entered when the MDIS bit in the MCR Register is asserted. When disabled, the module shuts down the clocks to the CAN Protocol Interface and Message Buffer Management sub-modules.."

The correct description is:

"This low power mode is entered when the MDIS bit in the MCR Register is asserted by the CPU. When disabled, the module requests to disable the clocks to the CAN Protocol Interface and Message Buffer Management sub-modules."

Section "Modes of Operation Details", Sub-section "Module Disable Mode":

Where is written:

"This low power mode is entered when the MDIS bit in the MCR Register is asserted. If the module is disabled during Freeze Mode, it shuts down the clocks to the CPI and MBM sub-modules, sets the LPM\_ACK bit and negates the FRZ\_ACK bit.."

The correct description is:

"This low power mode is entered when the MDIS bit in the MCR Register is asserted. If the module is disabled during Freeze Mode, it requests to disable the clocks to the CAN Protocol Interface (CPI) and Message Buffer Management (MBM) sub-modules, sets the LPM\_ACK bit and negates the FRZ\_ACK bit."

### **e352: FlexCAN: New feature - Individual RX matching and Message Queuing**

**Errata type:** Information

**Description:** The FlexCAN allows reception of the same message ID in multiple message buffers by setting the new Message Buffer Filter Enable control bit in the FlexCAN Module Configuration Register, CANx\_MCR[MBFEN] (bit 15). By programming more than one Message Buffer with the same ID or using a mask, received messages will be queued into the Message Buffers.

**Workaround:** For backwards software compatibility with the MPC5554, MPC5553, and the initial versions of the MPC5534, do not use this new feature or insure that the feature exists prior to their use.

### **e1654: FlexCAN: New feature - Self reception disable**

**Errata type:** Information

**Description:** The FlexCAN can now be configured to disallow reception of frames transmitted by itself by setting the Self Reception Disable bit in the FlexCAN Module Configuration Register (CANx\_MCR[SRXDIS]=0b1, bit 14).

**Workaround:** For backwards software compatibility with the MPC5554, MPC5553, and the initial versions of the MPC5534, do not use these new features or insure that the features exist prior to their use.

### **e1895: FlexCAN: New feature - Transmit (TX)/Receive (RX) Warning Interrupts**

**Errata type:** Information

**Description:** The Warning Interrupt bit has been added in the FlexCAN Module Configuration Register, CANx\_MCR[WRNEN] (bit 10). In addition two bits have been added in the FlexCAN Control Register, Transmit Warning Interrupt Mask, CANx\_CR[TWRNMSK] (bit 20) and the Receive Warning Mask, CANx\_CTRL[RWRNMSK] (bit 21) allow applications to enable monitoring for Transmit and Receive error counters and generate an interrupt for either if the error count reaches 96 errors or more. Consequently, two status bits have been added in the FlexCAN Error and Status register to signal interrupts for these additional interrupt causes, the Transmit Warning Interrupt bit (CANx\_ESR[TWRNINT], bit 14) and the Receive Warning Interrupt bit (CANx\_ESR[RWRNINT], bit 15). Both of these status bits are cleared by writing a 1 to the bit.

**Workaround:** For backwards software compatibility with the MPC5554, MPC5553, and the initial versions of the MPC5534, do not use this new feature or insure that the feature exists prior to their use.

### **e2424: FlexCAN: switching CAN protocol interface (CPI) to system clock has very small chance of causing the CPI to enter an indeterminate state**

**Errata type:** Errata

**Description:** The reset value for the clock source of the CAN protocol interface (CPI) is the oscillator clock. If the CPI clock source is switched to the system clock while the FlexCAN is not in freeze mode, then the CPI has a very small chance of entering an indeterminate state.

**Workaround:** Switch the clock source while the FlexCAN is in a halted state by setting HALT bit in the FlexCAN Module Configuration Register (CANx\_MCR[HALT]=1). If the write to the CAN Control Register to change the clock source (CANx\_CR[CLK\_SRC]=1) is done in the same oscillator clock period as the write to CANx\_MCR[HALT], then chance of the CPI entering an indeterminate state is extremely small. If those writes are done on different oscillator clock periods, then the corruption is impossible. Even if the writes happen back-to-back, as long as the system clock to oscillator clock frequency ratio is less than three, then the writes will happen on different oscillator clock periods.

### **e1620: MPC5533: PARTNUM is incorrect**

**Errata type:** Errata

**Description:** The Device Identification fields in the of the SIU\_MIDR[PARTNUM] incorrectly show that the device is a MPC5534 device. PARTNUM reads 0x5534.

**Workaround:** Do rely on the SIU\_MIDR[PARTNUM] or the JTAG device Identification to determine features available in the device. JTAG ID for the MPC5533 and the MPC5534 are the same.

### **e677: MPC5533: SIU\_MIDR Revision field is 0x0010, DID[PIN]=0x134**

**Errata type:** Information

**Description:** The part number field in the MCU Identification Register (SIU\_MIDR[PARTNUM]) is 0x5533. The mask revision number (SIU\_MIDR[MASKNUM]) is 0x10. The Part Number Identification field in the Nexus Port Controller Device Identification Register/JTAGC Identification Register (JTAGC\_ID/NPC\_DID[PIN]) has been changed to 0x134. The JTAGC\_ID/NPC\_DID[PRN] changed to 0x1. Note that the NPC\_DID[PIN] is the same as the NPC\_DID[PIN] on the MPC5534. The MPC5534 BSDL file should also be used for the MPC5533.

**Workaround:** Software should be aware that the SIU\_MIDR[MASKNUM] field can change in the future. Tools should be aware of the JTAGC\_ID/NPC\_DID[PIN]. In addition, tools should be aware that the revision number in the JTAG and Nexus ID could change in the future (JTAGC\_ID/NPC\_DID[PRN]).

### **e1795: MPC5534: Flash settings documentation is incorrect**

**Errata type:** Errata

**Description:** The MPC5534 Reference Manual included incorrect information on settings required for Flash Bus Interface (Flash\_BIU). The Address Pipelining Control (APC) and Read Wait State Control (RWSC) should always be set to the same value.

**Workaround:** Refer to updated documentation, either the MPC5534 Reference Manual Addendum (dated after August 2006), an updated MPC5534 Reference Manual (if available), the MPC5534 Electrical Specification (Data Sheet dated after August 2006) or refer to the following table for the correct settings for the Address Pipelining Control (APC), Read Wait State Control (RWSC), and Pipelined Reads Disabled (PRD).

Target Frequency

(Maximum) APC RWSC PRD

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Up to 25 MHz 0b000 0b000 0b1

Up to 50 MHz 0b001 0b001 0b0

Up to 75 MHz 0b010 0b010 0b0

Up to 80 MHz 0b011 0b011 0b0

The Write Wait State Control (WWSC) should be set to 0b01 for all frequencies. For maximum performance, the Data Prefetch Enable (DPFEN) and Instruction Prefetch Enable (IPFEN) should be set to 0b1, the Prefetch Limit (PFLIM) should be set to 0b110, and the bus interface line read buffers should be enabled (BFEN=0b1). In addition, the Master Prefetch Enable (MxPFE) should be set for each of the Master Cross Bar Master ID (not port number). [MxPFE should be set to 0xF for all Master IDs.] APC, RWSC, WWSC, DPFEN, IPFEN, PFLIM, and BFEN are in the Flash Bus Interface Control Register (FLASH\_BIU\_CR). PRD is in the Flash Module Configuration Register (FLASH\_MCR).

Note: this errata was updated 25 August 2006.

### **e1650: MPC5534: SIU\_MIDR Revision field is 0x0010, DID[PIN]=0x134**

**Errata type:** Information

**Description:** The part number field in the MCU Identification Register (SIU\_MIDR[PARTNUM]) is 0x5534. The mask revision number (SIU\_MIDR[MASKNUM]) is 0x10. The Part Number Identification field in the Nexus Port Controller Device Identification Register/JTAGC Identification Register (JTAGC\_ID/NPC\_DID[PIN]) has been changed to 0x134. The JTAGC\_ID/NPC\_DID[PRN] changed to 0x1.

**Workaround:** Software should be aware that the SIU\_MIDR[MASKNUM] field can change in the future. Tools should be aware of the JTAGC\_ID/NPC\_DID[PIN]. In addition, tools should be aware that the revision number in the JTAG and Nexus ID could change in the future (JTAGC\_ID/NPC\_DID[PRN]).

### **e6726: NPC: MCKO clock may be gated one clock period early when MCKO frequency is programmed as SYS\_CLK/8 and gating is enabled**

**Errata type:** Errata

**Description:** The Nexus auxiliary message clock (MCKO) may be gated one clock period early when the MCKO frequency is programmed as SYS\_CLK/8 in the Nexus Port Controller Port Configuration Register (NPC\_PCR[MCKO\_DIV]=111) and the MCKO gating function is enabled (NPC\_PCR[MCKO\_GT]=1). In this case, the last MCKO received by the tool prior to

the gating will correspond to the END\_MESSAGE state. The tool will not receive an MCKO to indicate the transition to the IDLE state, even though the NPC will transition to the IDLE state internally. Upon re-enabling of MCKO, the first MCKO edge will drive the Message Start/End Output (MSEO=11) and move the tool's state to IDLE.

**Workaround:** Expect to receive the MCKO edge corresponding to the IDLE state upon re-enabling of MCKO after MCKO has been gated.

### e1957: NPC: MCKO\_DIV can be set to 0x0 (1X MCKO)

**Errata type:** Information

**Description:** The Nexus Port Controller Port Configuration Register MCKO Divider bits (NPC\_PCR[MCKO\_DIV]) can be set to 0b000 to select a 1X clock rate as the Nexus Auxiliary output port frequency for the MCKO and MDO pins. Note: Depending on the system frequency, this may force the MCKO and MDO pins to switch at a frequency higher than can be supported by the pins. This maximum frequency is specified in the device electrical specification of the Nexus MCKO and MDO pins.

**Workaround:** Insure that the maximum operating frequency of the MDO and MCKO pins is not violated when setting the NPC\_PCR[MCKO\_DIV] values.

Note: tools may not support 1X mode. Check with your tool vendor.

### e1717: NZ3C3: Data Trace of stmw instructions may cause overruns

**Errata type:** Information

**Description:** If Nexus data trace is enabled on a section of memory that is loaded or stored with a store multiple word (stmw), or load multiple word (lmw for data read traces), an overrun condition could occur, even if the stall on overrun feature is enabled (NZ3C3\_DC1[OVC]=0b011). The stmw/lmw instructions can generate up to 16 Nexus trace messages with a single instruction. If there are not 16 queue locations available, an overflow will occur. Stall mode does not stall the core until there are only four locations available in the e200 Nexus message queue. Therefore if a stmw/lmw generates more than four messages, the queue will overflow. the stmw/lmw instructions load or store two 32-bit registers at a time (64-bit stores/loads) if an even number of registers are selected.

**Workaround:** If stall mode is enabled (NZ3C3\_DC1[OVC]=0b011), limiting store multiple word instruction in a data trace region to store/load 8 registers or less, will improve the chances that an overrun will not occur, but this is dependent on other messages that could be generated simultaneously with the data trace messages. If stall mode is disabled, or stmw instructions with more than 8 registers are stored, accept overruns in the data trace flow.

### e597: NZ3C3: Nexus I-CNT same for Indirect Branches and Exceptions

**Errata type:** Errata

**Description:** The e200z3 core Nexus (NZ3C3) transmits a Program Trace Indirect Branch message without indicating if the message was sent due to a taken branch or due to an exception. The instruction count (I-CNT) for an exception now includes branches in the completed I-CNTs.

**Workaround:** Trace reconstruction tools should be aware that the I-CNT for Exceptions and for Indirect Branches are now the same. The tool may need to know (from the user or by parsing registers) the exception handler addresses from the Interrupt vector prefix register (IVPR) and the Interrupt vector offset registers (IVORxx). Users also should not jump directly to interrupt handler addresses. Tools can then differentiate between exceptions and indirect branches.

### **e1727: NZ3C3: No sync message generated after 255 direct branch messages in history mode**

**Errata type:** Information

**Description:** When using the branch history mode of direct branch program trace in the e200z3 core, a synchronization message is not transmitted after 255 program trace messages in a row. This will occur if resource full messages are sent and not counted for triggering a sync message indicating that the branch history fields are full. The resource full message is generated when more than 31 direct branches occur without an indirect branch or exception.

**Workaround:** Debuggers should account for the possibility that more than 255 messages could be received without a program trace synchronization message by keeping track of the last known program trace address prior to branch history resource full messages.

### **e1886: Pad Ring: ESD Specifications are not met**

**Errata type:** Errata

**Description:** Not all pins of the device meet the ESD specifications of 2000 volts Human Body Model (HBM), specifically negative ESD from pins outside of the VRC domain referenced to either VRC33 or VRCCTL fail at 500 volts. In addition, and the TEST pin fails above 1500 volts.

All pins meet the ESD specifications using the Field Induced Charged Device Model (CDM - per AEC Q100-002), except in the 208 MAPBGA package. In the 208 MAPBGA package some analog input pins (ANx) fail the CDM specification at 500 volts (passes at 250 volts).

**Workaround:** Avoid exposure of the VRCCTL, VRC33, and TEST pins to human body ESD events prior to mounting onto a printed circuit board (PCB). Also, avoid exposure of the Analog pins to voltages above 250V for CDM type ESD when using the 208 MAPBGA package. PCB will provide protection after being mounted. Minimize exposure of the other pins to human body type ESD events greater than 2000 volts.

### **e1528: Pad Ring: Pin behavior during power sequencing**

**Errata type:** Information

**Description:** The power sequence pin states table in the device data sheet (electrical specification) did not specify the influence of the weak pull devices on the output pins during power up. When VDD is sufficiently low to prevent correct logic propagation, the pins may be pulled high to VDDE/VDDEH by the weak pull devices.

At some point prior to exiting the internal power-on reset state, the pins will go high-impedance until POR is negated.

When the internal POR state is negated, the functional state during reset will apply and weak pull devices (up or down) will be enabled as defined in the device Reference Manual.

**Workaround:** The best solution is to minimize the ramp time of the VDD supply to a time period less than the time required to enable external circuitry connected to the device outputs.

### **e488: Pad Ring: Possible poor system clock just after POR negation.**

**Errata type:** Information

**Description:** The pins RSTCFG\_B and PLLCFG[0:1] select one of three PLL modes or allows a clock to be injected, bypassing the PLL. When Power On Reset (POR) negates, if the transitions on these pins selects the bypass mode, a poor clock on EXTAL can provide a poor clock to MCU logic no longer reset by POR. The state of that logic can be corrupted.

**Workaround:** If the default PLL and Boot configuration (external crystal reference and boot from internal flash) will be used, then negate the RSTCFG pin (=1). For any other configuration, depending on the final mode required, the pins must have the following values on the pins when the internal POR negates.

Final Mode RSTCFG\_B PLLCFG[0] PLLCFG[1]

default 1 - -

external reference 0 1 1

external crystal - 1 -

dual controller - 1 -

After POR negates, the RSTCFG\_B and PLLCFG[0:1] can be changed to their final value, but should avoid switching through the 0,0,0 state on these pins. See application note AN2613 "MPC5554 Minimum Board Configuration" for one example off the external configuration circuit.

### **e1969: Pad Ring: RSTOUT is 3-stated during the power-on sequence.**

**Errata type:** Information

**Description:** RSTOUT\_B is 3-stated during power on reset.

**Workaround:** Connect an external pull device to RSTOUT\_B during power on reset. This should be pull-down unless an external reset configuration circuit is being used, in which case it should be pull-up. Refer to AN2613 'MPC5554 Minimum Board Configurations' for further information.

### **e3377: Pad Ring:Nexus pins may drive an unknown value immediately after power up but before the 1st clock edge**

**Errata type:** Errata

**Description:** The Nexus Output pins (Message Data outputs 0:15 [MDO] and Message Start/End outputs 0:1 [MSEO]) may drive an unknown value (high or low) immediately after power up but before the 1st clock edge propagates through the device (instead of being weakly pulled low). This may cause high currents if the pins are tied directly to a supply/ground or any low resistance driver (when used as a general purpose input [GPI] in the application).

**Workaround:** 1. Do not tie the Nexus output pins directly to ground or a power supply.

2. If these pins are used as GPI, limit the current to the ability of the regulator supply to guarantee correct start up of the power supply. Each pin may draw upwards of 150mA. If not used, the pins may be left unconnected.

### **e1779: SIU: CRSE bit added to the SIU Configuration Register**

**Errata type:** Information

**Description:** A new bit was added to the System Integration Unit to disable driving both the normal external bus and the calibration bus interface.

The Calibration Reflection Suppression Enable (SIU\_CCR[CRSE]) bit enables the suppression of reflections from the External Bus Interface's calibration bus onto the non-calibration bus. The EBI drives some outputs to both the calibration and non-calibration busses. When CRSE is asserted (0b1), the values driven onto the calibration bus pins will not be reflected onto the non-calibration bus pins. When CRSE is negated (0b0), the values driven onto the calibration bus pins will be reflected onto the non-calibration bus pins. CRSE only enables reflection suppression for non-calibration bus pins that do not have a negated state to which the pins return at the end of the access. CRSE does not enable reflection suppression for the non-calibration bus pins that have a negated state to which the pins return at the end of an access. Those reflections always are suppressed. Furthermore, the suppression of reflections from the non-calibration bus onto the calibration bus is not enabled by CRSE. Those reflections also always are suppressed.

**Workaround:** Set the CRSE bit in the SIU\_CCR to prevent signals on the calibration bus from being reflected onto the normal external bus interface.

### **e1053: XBAR: Illegal values can be written into the Master Priority Field**

**Errata type:** Errata

**Description:** The Crossbar switch (XBAR) should not allow illegal values to be written to the Slave port's Master Priority Register (XBAR\_MPRx). All valid Master Priority fields (MSTRx) of the XBAR\_MPRx must be written with unique values. On devices that only support 2 bits for the Master Priority Field (MSTRx), if unique 3 bit values are written to the XBAR\_MPRx[MSTRx] that contain the same 2-bit value (only 2 of the bits are written into each field), the illegal value will be written into the register and cause an illegal state. For example, if 0b101 is written into one MSTRx and 0x001 is written to another MSTRx field in the same slave MPRx, both fields will result in the same 2 bit value (0b01).

**Workaround:** Software must insure that unique 2-bit values are written to the Master Priority Register Master Priority Fields.

### **e1813: e200z3: Debug interrupt (IVOR15) can be taken erroneously**

**Errata type:** Errata

**Description:** If instruction complete debug events are enabled in the Debug Control Register 0 (DBCR0[ICMP] = 1) and an external interrupt causes a load multiple word, store multiple word, integer divide, or floating point divide instruction to be interrupted prior to completion, a debug interrupt will be taken erroneously instead of the external interrupt. If external debug mode is enabled in the Debug Control Register 0 (DBCR0[EDM] = 1), debug mode will be entered after fetching the first instruction of the debug interrupt handler.

**Workaround:** Use the Go+NoExit method of single stepping in the OnCE Command Register (OCMD[GO] = 1, OCMD[EX] = 0) if external debug mode is enabled in the Debug Control Register 0 (DSCR0[EDM] = 1). If single stepping is implemented using instruction complete debug events, disable external interrupts (MSR[EE] = 0) prior to stepping over a load multiple word, store multiple word, integer divide, or floating point divide instruction.

### **e1682: e200z3: JTAG Part Identification is 0x6**

**Errata type:** Information

**Description:** The Part Identification Number (PIN) in the e200z3 core JTAG and Nexus device identification messages and register (NZ3C3\_DID) is 0x6. The complete e200z3 JTAG ID and DID is 0x07C0601D.

**Workaround:** Tools that use the e200z3 DID should expect updated values to identify the PowerPC core or use the complete device Nexus Port Controller DID message/register.

### **e1136: eDMA: BWC setting may be ignored between 1st and 2nd transfers and after the last write of each minor loop.**

**Errata type:** Errata

**Description:** The eDMA Transfer Control Descriptor Bandwidth Control field setting may be ignored between 1st and 2nd transfers and after the last write of each minor loop. This will occur if the source and destination sizes are equal. This behavior is a side effect of measures designed to reduce start-up latency. Reference Manuals may fail to mention this behavior.

**Workaround:** There are 2 possible workarounds:

- 1) Adjust the Transfer Control Descriptor (TCD) to make the source size not equal to the destination sizes (i.e. ssize = 16 bit, dsize = 32 bit). This delays the write which allows BWC[0:1] arriving from the TCD to be considered in the execution pipeline during start-up.
- 2) Adjust the TCD so the channel executes a single read/write sequence and then retires. In addition, the channel can be configured to execute a minor loop link to itself which will restart the channel after arbitration and channel start-up latency. The total number of bytes transferred can be controlled by the major loop count.

### **e1834: eMIOS: OPWMC unable to produce close to 100% duty cycle signal**

**Errata type:** Errata

**Description:** The Center Aligned Output Pulse Width Modulation with Dead-time Mode (OPWMC) of the eMIOS module does not function correctly if the trailing edge dead time is programmed to a value outside of the current cycle time. The OPWMC mode requires that matches occur in the specific order: A, A, and then B, where the first A must match on the up count of the modulus counter, the second A match occurs on the down count of the modulus counter, and the B match occurs on the internal counter. If the programmed B match value is greater than the time required for the modulus counter to count down from the second A match and then up to the first A match of the next cycle, the first A match of the next cycle will be missed and the mode will not function correctly from that point on.

**Workaround:** Configure the selected modulus counter time base and the internal counter of the channel in OPWMC mode to count at the same rate. Program the value of the B match (dead time) to a value less than 2 times the programmed A match value.

### **e1769: eMIOS: Updating the B register requires 32-bit writes.**

**Errata type:** Errata

**Description:** 8-bit writes to the least significant 8 bits of the eMIOS Channel B Data register (eMIOS\_CBDRn) actually cause a 32-bit write to the entire register, potentially corrupting the upper 24-bits of the register.

**Workaround:** Use only 32-bit accesses to write to eMIOS Channel B Data Register. If a single byte is to be modified, read the register, modify the byte, and write the entire register back as a 32-bit write.

### **e1773: eQADC: conversions of muxed digital/analog channels close to the rail**

**Errata type:** Information

**Description:** If the VDDEH9 and the VDDA power supplies are at different voltage levels, the input clamp diodes on the multiplexed digital and analog signals (AN12, AN13, AN14, and AN15) will clamp to the lower of the two supplies.

If VDDEH9 is lower than the VDDA, conversions on these channels will not obtain full scale readings if voltage is close the the VDDA voltage.

**Workaround:** When multiplexed digital/analog signals are used as analog inputs, connect VDDEH9 to VDDA and do not use any of the digital functions multiplexed on these pins.

### **e1013: eSCI : Automatic reset of the LIN state machine cause incorrect transmission**

**Errata type:** Errata

**Description:** When the LIN FSM of the eSCI module performs an automatic reset due to a bus error condition, it is possible that the application is no longer synchronized to the LIN FSM. As a result, the eSCI may consider the payload data provided by the application via the LIN Transmit Register (eSCI\_LTR) as a LIN frame header data and will generate an unexpected LIN frame.

**Workaround:** The application should disable the automatic LIN FSM reset functionality by setting LDBG bit in the LIN Control Register (eSCI\_LCR) to 1.

### **e1381: eSCI: LIN Wakeup flag set after aborted LIN frame transmission**

**Errata type:** Errata

**Description:** If the eSCI module is transmitting a LIN frame and the application sets and clears the LIN Finite State Machine Resync bit in the LIN Control Register 1 (eSCI\_LCR1[LRRES]) to abort the transmission, the LIN Wakeup Receive Flag in the LIN Status Register may be set (LWAKE=1).

**Workaround:** If the application has triggered LIN Protocol Engine Reset via the eSCI\_LCR1[LRES], it should wait for the duration of a frame and clear the eSCI\_IFSR2[LWAKE] flag before waiting for a wakeup.

### **e1221: eSCI: LIN bit error indicated at start of transmission after LIN reset**

**Errata type:** Errata

**Description:** If the eSCI module is in LIN mode and is transmitting a LIN frame, and the application sets and subsequently clears the LIN reset bit (LRES) in the LIN Control register 1 (ESCI\_LCR1), the next LIN frame transmission might incorrectly signal the occurrence of bit errors (ESCI\_IFSR1[BERR]) and frame error (ESCI\_IFSR1[FE]), and the transmitted frame might be incorrect.

**Workaround:** There is no generic work around. The implementation of a suitable workaround is highly dependent on the application and a workaround may not be possible for all applications.

### **e1017: eSCI: LIN fast bit error detection causes incorrect LIN reception**

**Errata type:** Errata

**Description:** When using the eSCI module in LIN mode, if the fast bit error detection is enabled in the eSCI Control Register 2 (eSCIx\_CR2[FBR]) and a bit distortion occurs on the RX line, the eSCI module may process the bit error signal incorrectly. This may cause unexpected transmission and reception behavior of the LIN state machine.

**Workaround:** The application should disable the fast bit error detection by setting the FBR bit to 0.

### **e2190: eSCI: LIN slave timeout flag STO not asserted if CRC is received too late**

**Errata type:** Errata

**Description:** The eSCI module will not assert the Slave-Timeout Flag (STO) in the eSCI LIN Status Register 1 (LINSTAT1) if the checksum field of on RX frame is received later than the time given in the Timeout Value (TO) field of the LIN RX control header.

If the checksum field of on RX frame is not received at all, The STO flag will not be set and the LIN FSM will wait forever.

**Workaround:** The application should use a timer external to the eSCI module, that is started when a LIN RX frame transmission is started with an expiration time programmed to the expected duration of the reception. The timer is stopped, when the eSCI module signals the end of the LIN frame reception. If this timer expires, the eSCI has ran into the slave timeout condition. In this case, the application should clear the SCICR2[TE] and SCICR2[RE] bits to disable the transmitter and receiver, and should set the LINCTRL1[LRES] bit the reset the eSCI internal LIN slave and master tasks. To resume LIN frame data transmission the application should enable the transmitter and receiver and clear the LINCTRL1[LRES] bit to enable the LIN slave and master tasks.

## **e1614: eSCI: Low pulse on LIN RX line may prevent assertion of transmit data ready flag ESCI\_SR[TXRDY]**

**Errata type:** Errata

**Description:** If the eSCI module is in LIN mode and receives a low pulse on the RX line while transmitting a frame header or a stop bit, the eSCI internal LIN master and slave tasks may be stopped, and the transmit data ready flag ESCI\_SR[TXRDY] will never be asserted again.

Each of the following scenarios of the RX low pulse may provoke this erroneous behavior.

- a) The low pulse begins less than 12 bits before the start of the break character, and ends at least 21 bits and at most 30 bits after the start of the break character.
- b) The low pulse begins at least 13 bits and at most 14 bits after the start of the break character, and ends at least 22 bits after the start of the break character.
- c) The low pulse begins during the stop bit and has duration of at least 2 bits.

**Workaround:** The application should use a timer external to the eSCI module, that is started when a LIN frame transmission is started with an expiration time programmed to the expected duration of the transmission. The timer is stopped, when the eSCI module signals the end of the LIN frame transmission.

If this timer expires, the eSCI tasks have been stopped internally. In this case, the application should clear the Transmit Enable (SCICR2[TE]) and the Receive Enable (SCICR2[RE]) bits to disable the transmitter and receiver, and should set the LIN FSM resync (LINCTRL1[LRES]) bit to reset the eSCI internal LIN slave and master tasks.

To resume LIN frame data transmission the application should enable the transmitter and receiver and clear the LINCTRL1[LRES] bit to enable the LIN slave and master tasks.

## **e644: eTPU: MISSCNT can fail on sequential physical teeth**

**Errata type:** Errata

**Description:** If the eTPU Angle Counter (EAC) detects a physical tooth with a non-zero value in the Missing Tooth Counter (MISSCNT) field of the Tooth Program Register (TPR), and during high-rate mode MISSCNT is written with a non-zero value, MISSCNT resets at the end of the high-rate mode.

One example of this use case is when the tooth wheel has more than 3 consecutive missing teeth, and MISSCNT is re-written with a non-zero value to support the extra missing teeth.

Another possible use case can occur when transitioning from normal tooth signal to a backup signal coming from a cam signal, for example.

These examples are illustrative, and do not exhaust the possibilities for the occurrence of the situation described.

**Workaround:** If a non-zero value is written to TPR[MISSCNT] and another non-zero value must be written after a single physical tooth is detected, the second non-zero value write should coincide with a match service on the TCR2 value estimated for the tooth. This will avoid MISSCNT being written in high-rate mode.

## e112: eTPU: Prescaler phase shift between TCR1 and TCR2

**Errata type:** Information

**Description:** The Timer Counter Register 1 (TCR1) and Timer Counter Register 2 (TCR2) prescalers are initialized at slightly different times when the Global Timebase Enable (GTBE) is enabled. A phase shift of up to 2 clocks (one microcycle) can occur when the Timer Counter Registers (TCR1 and TCR2) increment in common multiples of the prescaler ratio.

**Workaround:** Expect a phase shift of up to 2 system clocks (one eTPU microcycle) between TCR1 and TCR2. TCR1 increments before TCR2.

## e1728: eTPU: STAC bus export may skip 1 count

**Errata type:** Errata

**Description:** If the eTPU Angle Clock (EAC) is enabled and exported on the Shared Time and Counter bus (STAC) then one count may be skipped on random occasions. This only happens when the EAC transitions from Halt or High-rate mode to normal mode and the integer part of the Tick Rate Register (TRR) inside the eTPU is equal to 1. This skip does not occur on the TCR2 bus internal to the eTPU engine generating the angle clock.

**Workaround:** Either (1) use only greater-than-or-equal comparisons on angle counts imported from the STAC bus; or (2) limit the TRR integer part to 2 minimum. If  $TRR(\text{integer}) = 1$  is a needed rate for maximum performance, the new TRR limitation can be compensated by either:

- (a) doubling the TCR1 rate (for instance halving the TCR1 prescaler division), or
- (b) halving the number of ticks per tooth (sacrificing angle accuracy).

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